

THC63LVD827

LOW POWER / SMALL PACKAGE / 24Bit COLOR LVDS TRANSMITTER

General Description

The THC63LVD827 transmitter is designed to support pixel data transmission between Host and Flat Panel Display and Dual Link transmission between Host and Flat Panel Display up to 1080p/1920x1200 resolutions.

The THC63LVD827 converts 27bits (RGB 8 bits + Hsync, Vsync, DE) of CMOS/TTL data into LVDS (Low Voltage Differential Signaling) data stream. The transmitter can be programmed for rising edge or falling edge clocks through a dedicated pin.

For dual LVDS out, LVDS clock frequency of 87MHz, 51bits of RGB data are transmitted at an effective rate of 609Mbps per LVDS channel.

For single LVDS out, LVDS clock frequency of 174MHz, 27bits of RGB data are transmitted at an effective rate of 1218Mbps per LVDS channel.

21bits (RGB 6 bits + Hsync, Vsync, DE) mode is also selectable for 6bit color transmission with lower power.

Features

- Low power 1.8V CMOS design
- 7mm x 7mm/72pin/0.65mm pitch/TFBGA package applicable to non-HDI PCB.
- Wide dot clock range, 10-174MHz, suited for TV Signal: up to 1080p(74.25MHz dual)
PC Signal: up to 1920x1200(77MHz dual)
- Supports 1.8V single power supply
- 1.8V/2.5V/3.3V TTL/CMOS inputs are supported by setting IOVCC=1.8V/2.5V/3.3V
- LVDS swing reducible by RS-pin to reduce both EMI and power consumption
- PLL requires No external components
- Flexible Input / Output mode
 1. Single in / Dual LVDS out
 2. Single in / Single LVDS out
 3. Double edge Single in / Dual LVDS out
- 2 LVDS data mapping to simplify PCB layout
- Power down mode
- Input clock triggering edge selectable by R/F pin
- 6bit / 8bit modes selectable by 6B/8B pin

Block Diagram

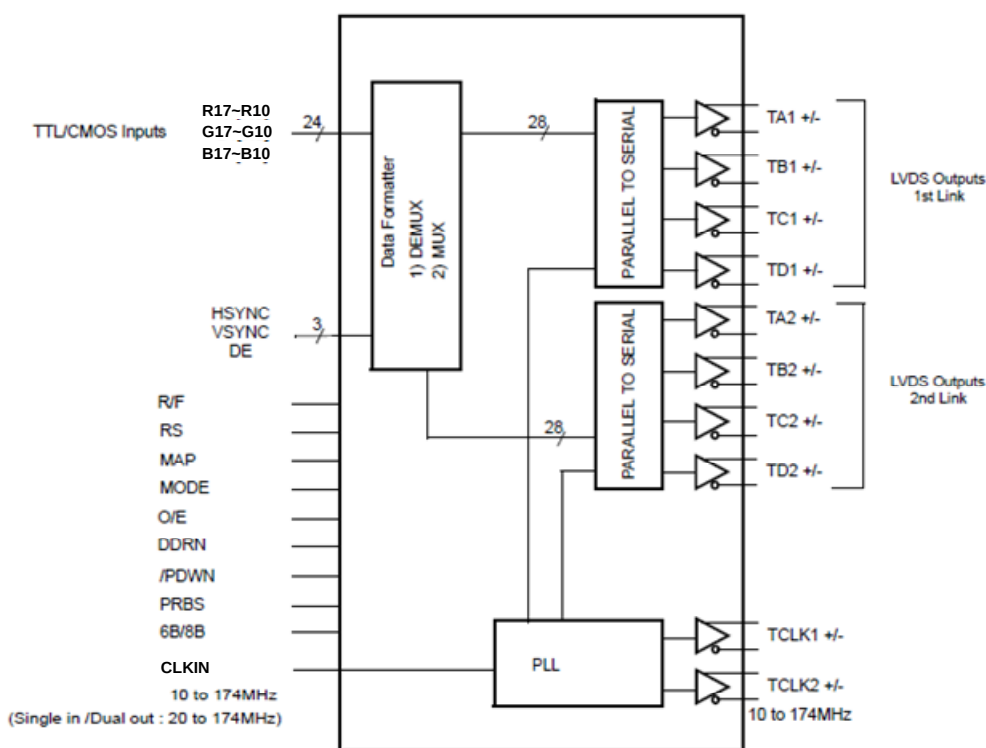


Figure 1. Block Diagram

Pin Diagram (top view)

TOP VIEW										
	1	2	3	4	5	6	7	8	9	
A	TA1+	TB1+	TC1+	TCLK1 +	TD1+	TA2+	TB2+	TC2+	TCLK2 +	A
B	TA1-	TB1-	TC1-	TCLK1 -	TD1-	TA2-	TB2-	TC2-	TCLK2 -	B
C	PRBS	N/C	Reserved1	GND	LVDS VCC	GND	PLL VCC	TD2-	TD2+	C
D	R11	R10	LVDS VCC				GND	/PDWN	O/E	D
E	R13	R12	GND				MODE	MAP	DDRN	E
F	R15	R14	GND				6B/8B	RS	CLKIN	F
G	R17	R16	VCC	GND	VCC	GND	IOVCC	R/F	DE	G
H	G10	G12	G14	G16	B10	B12	B14	B16	VSYNC	H
J	G11	G13	G15	G17	B11	B13	B15	B17	HSYNC	J
	1	2	3	4	5	6	7	8	9	

Figure 2. Pin Diagram

Pin Description

Pin Name	Pin #	Type	Description						
TA1+,TA1-	A1,B1	LVDS OUT	The 1st Link. The 1st pixel output data when Dual out. Output data when Single out.						
TB1+,TB1-	A2,B2								
TC1+,TC1-	A3,B3								
TD1+, TD1-	A5,B5		LVDS Clock Out for 1st Link.						
TCLK1+, TCLK1-	A4,B4								
TA2+,TA2-	A6,B6								
TB2+,TB2-	A7,B7		The 2nd Link. The 2nd pixel output data when Dual out.						
TC2+,TC2-	A8,B8								
TD2+, TD2-	C9,C8								
TCLK2+, TCLK2-	A9,B9		LVDS Clock Out for 2nd Link.						
R17~R10	G1,G2,F1,F2 E1,E2,D1,D2	IN	Pixel Data Inputs.						
G17~G10	J4,H4,J3,H3 J2,H2,J1,H1								
B17~B10	J8,H8,J7,H7 J6,H6,J5,H5								
DE	G9	IN	Data Enable Input.						
VSYNC	H9	IN	Vsync Input.						
HSYNC	J9	IN	Hsync Input.						
CLKIN	F9	IN	Clock Input.						
R/F	G8	IN	Input Clock Triggering Edge Select. H: Rising edge, L: Falling edge						
RS	F8	IN	LVDS swing mode select. <table><tr><td>RS</td><td>LVDS Swing(V_{OD}, see Fig.7 and Fig.8)</td></tr><tr><td>H</td><td>350mV</td></tr><tr><td>L</td><td>200mV</td></tr></table>	RS	LVDS Swing(V _{OD} , see Fig.7 and Fig.8)	H	350mV	L	200mV
RS	LVDS Swing(V _{OD} , see Fig.7 and Fig.8)								
H	350mV								
L	200mV								
MAP	E8	IN	LVDS mapping table select. See Fig.12 and Fig.13. <table><tr><td>MAP</td><td>Mapping Mode</td></tr><tr><td>H</td><td>Mapping MODE1</td></tr><tr><td>L</td><td>Mapping MODE2</td></tr></table>	MAP	Mapping Mode	H	Mapping MODE1	L	Mapping MODE2
MAP	Mapping Mode								
H	Mapping MODE1								
L	Mapping MODE2								
MODE	E7	IN	Pixel data mode. See Fig.10 and Fig.11. <table><tr><td>MODE</td><td>Modes</td></tr><tr><td>H</td><td>Single out (Single-in / Single-out)</td></tr><tr><td>L</td><td>Dual out (Single-in / Dual-out)</td></tr></table>	MODE	Modes	H	Single out (Single-in / Single-out)	L	Dual out (Single-in / Dual-out)
MODE	Modes								
H	Single out (Single-in / Single-out)								
L	Dual out (Single-in / Dual-out)								
O/E	D9	IN	Output enable H: Output enable. L: Output disable (all outputs are Hi-Z).						
/PDWN	D8	IN	Power Down enable H: Normal operation. L: Power down (all outputs are Hi-Z and all circuits are stand-by mode with minimum current (I _{TCCS})).						
PRBS (*a)	C1	IN	Must be tied to GND.						

Pin Description (Continued)

Pin Name	Pin #	Type	Description
Reserved1	C3	IN	Must be tied to GND.
6B/8B	F7	IN	6bit / 8bit mode select. H: 6bit mode (21bit mode), L: 8bit mode (27bit mode).
DDRN	E9	IN	DDR function is active when MODE=L (Dual-out mode) H: DDR (Double Edge input) function disable (Fig.7). L: DDR (Double Edge input) function enable (Fig.8).
N/C	C2	-	Must be Open.
VCC	G3,G5	Power	Power Supply Pins for digital circuitry.
IOVCC	G7		Power Supply Pins for IO inputs circuitry.
LVDSVCC	C5,D3		Power Supply Pins for LVDS Outputs.
PLLVC	C7		Power Supply Pins for PLL circuitry.
GND	F3,G4,G6,C4, E3,C6,D7	Ground	Ground Pins.

(*a) : Setting the PRBS pin high enables the internal test pattern generator. It generates Pseudo-Random Bit Sequence of $2^{23}-1$.

The generated PRBS is fed into input data latches, encoded and serialized into LVDS OUT.

This function is normally to be used for analyzing the signal integrity of the transmission channel including PCB traces, connectors, and cables.

Absolute Maximum Ratings

Parameter	Min	Max	Unit
Power Supply Voltage (IOVCC)	-0.3	+4.0	V
Power Supply Voltage (VCC, PLLVCC, LVDSVCC)	-0.3	+2.1	V
CMOS/TTL Input Voltage	-0.3	IOVCC+0.3	V
LVDS Transmitter Output Voltage	-0.3	LVDSVCC+0.3	V
Output Current	-50	+50	mA
Junction Temperature	-	+125	°C
Storage Temperature Range	-55	+125	°C
Reflow Peak Temperature / Time	-	+260 / 10sec	°C
Maximum Power Dissipation @+25°C	-	1.3	W

Recommended Operating Conditions

Symbol	Parameter				Min	Typ	Max	Unit
T_a	Operating Ambient Temperature				-40	25	+85	°C
IOVCC	Power Supply Voltage				1.62	1.8 2.5 3.3	3.6	V
PLLVCC LVDSVCC VCC	Power Supply Voltage				1.62	1.8	1.98	V
F_{clk}	Clock Frequency	MODE = L Dual - out	Single Edge Input (DDRN=H)	Input	20	-	174	MHz
				LVDS Output	10	-	87	
			Double Edge Input (DDRN=L)	Input	10	-	174	
				LVDS Output	10	-	174	
		MODE=H Single - out		Input	10	-	174	
				LVDS Output	10	-	174	

Electrical Characteristics

CMOS/TTL (Pin type “IN”) DC Specifications

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IH18}	High Level Data Input Voltage	IOVCC=1.62V~1.98V	0.65*IOVCC	-	IOVCC	V
V_{IL18}	Low Level Data Input Voltage		GND	-	0.35*IOVCC	V
V_{IH25}	High Level Data Input Voltage	IOVCC=2.3V~2.7V	1.7	-	IOVCC	V
V_{IL25}	Low Level Data Input Voltage		GND	-	0.7	V
V_{IH33}	High Level Data Input Voltage	IOVCC=3.0V~3.6V	2.0	-	IOVCC	V
V_{IL33}	Low Level Data Input Voltage		GND	-	0.8	V
I_{INC}	Input Current	VIN=GND~IOVCC	-10	-	+10	μ A

LVDS Transmitter (Pin type “LVDS OUT”) DC Specifications

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{OD}	Differential Output Voltage	$R_L = 100\Omega$	Normal swing RS=H	250	350	450	mV
			Reduced swing RS=L	140	200	300	
ΔV_{OD}	Change in V_{OD} between complementary output states	$R_L = 100\Omega$		-	-	35	V
V_{OC}	Common Mode Voltage			1.125	1.25	1.375	
ΔV_{OC}	Change in V_{OC} between complementary output states			-	-	35	
I_{OS}	Output Short Circuit Current	$V_{OUT}=GND, R_L = 100\Omega$		-	-	100	mA
I_{OZ}	Output TRI-State Current	/PDWN=L, $V_{OUT} = GND \sim LVDSVCC$		-20	-	+20	μ A

Electrical Characteristics (Continued)

Power Supply Current

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions			Typ(a)	Max(b)	Unit
I _{TCCW}	Operating Current	R _L =100Ω CL=5pF RS=H (RS=L)	MODE = H Single - out	CLKIN=37MHz	24 (18)	33 (26)	mA
				CLKIN=65MHz	29 (23)	43 (37)	
				CLKIN=72MHz	30 (24)	46 (40)	
			MODE = L Dual - out	CLKIN=89MHz	48 (36)	65 (53)	
				CLKIN=119MHz	53 (41)	75 (63)	
				CLKIN=139MHz	56 (44)	82 (70)	
			DDRN = H DDR Input Off	CLKIN=154MHz	58 (46)	88 (76)	
				CLKIN=44.5MHz	47 (35)	64 (52)	
			MODE = L Dual - out	CLKIN=59.5MHz	51 (39)	74 (62)	
				CLKIN=69MHz	54 (42)	80 (68)	
			DDRN = L DDR Input On	CLKIN=77MHz	56 (44)	85 (73)	
I _{TCCS}	Power Down Current	/PDWN = L, All Inputs = Fixed L or H			1	50	μA

(a) All Typ. values are at VCC=1.8V, Ta=25°C . The 256 Grayscale Test Pattern inputs test for a typical display pattern.

(b) All Max. values are at VCC=1.98V, Ta=105°C . Worst Case Test Pattern produces maximum switching frequency for all the LVDS outputs (Fig.3).

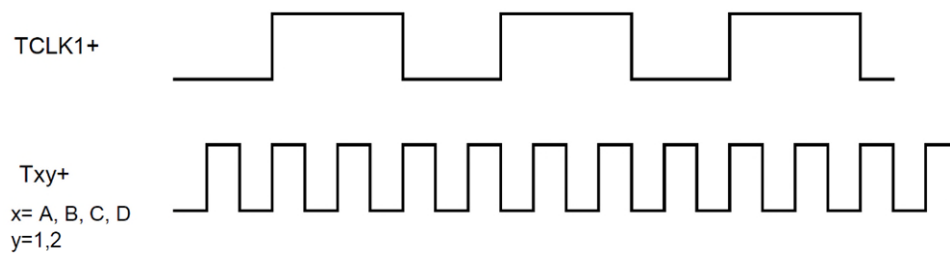


Figure 3. Test Pattern (LVDS Output Full Toggle Pattern)

Switching Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter		Min	Typ	Max	Unit
tTCIP	CLKIN Period (Fig.7,8)		5.75	-	100	ns
tTCH	CLKIN High Time (Fig.7,8)		0.35tTCIP	0.5tTCIP	0.65tTCIP	ns
tTCL	CLKIN Low Time (Fig.7,8)		0.35tTCIP	0.5tTCIP	0.65tTCIP	ns
tTS	TTL Data Setup to CLK IN (Fig.7,8)		0.8	-	-	ns
tTH	TTL Data Hold to CLK IN (Fig.7,8)		0.8	-	-	ns
tTCD	CLKIN to TCLK+/- Delay (Fig7,8)	MODE=L,DDRN=H	9tTCIP +3.1	-	9tTCIP +8.0	ns
		Others	5tTCIP +3.1	-	5tTCIP +8.0	ns
tTCOP	TCLK1,2 Period (Fig.6)		5.75	-	100	ns
tLVT	LVDS Transition Time (Fig.4)		-	0.6	1.5	ns
tTOP1	Output Data Position0 (Fig.9)	tTCOP =5.75ns~15ns	-0.15	0.0	+0.15	ns
tTOP0	Output Data Position1 (Fig.9)		$\frac{t_{TCOP}}{7}$ -0.15	$\frac{t_{TCOP}}{7}$	$\frac{t_{TCOP}}{7}$ +0.15	ns
tTOP6	Output Data Position2 (Fig.9)		$2 \frac{t_{TCOP}}{7}$ -0.15	$2 \frac{t_{TCOP}}{7}$	$2 \frac{t_{TCOP}}{7}$ +0.15	ns
tTOP5	Output Data Position3 (Fig.9)		$3 \frac{t_{TCOP}}{7}$ -0.15	$3 \frac{t_{TCOP}}{7}$	$3 \frac{t_{TCOP}}{7}$ +0.15	ns
tTOP4	Output Data Position4 (Fig.9)		$4 \frac{t_{TCOP}}{7}$ -0.15	$4 \frac{t_{TCOP}}{7}$	$4 \frac{t_{TCOP}}{7}$ +0.15	ns
tTOP3	Output Data Position5 (Fig.9)		$5 \frac{t_{TCOP}}{7}$ -0.15	$5 \frac{t_{TCOP}}{7}$	$5 \frac{t_{TCOP}}{7}$ +0.15	ns
tTOP2	Output Data Position6 (Fig.9)		$6 \frac{t_{TCOP}}{7}$ -0.15	$6 \frac{t_{TCOP}}{7}$	$6 \frac{t_{TCOP}}{7}$ +0.15	ns
tTPLL	Phase Lock Time (Fig.5)		-	-	10.0	ms
tDEINT	DE Input Period (Fig.6) Dual out mode only(MODE=L)		4tTCIP	tTCIP *(2n) ^(a)	-	ns
tDEH	DE Input Period (Fig.6) Dual out mode only(MODE=L)		2tTCIP	tTCIP *(2m) ^(a)	-	ns
tDEL	DE Input Period (Fig.6) Dual out mode only(MODE=L)		2tTCIP	-	-	ns

(a) Refer to Fig.6 for details.

AC Timing Diagrams

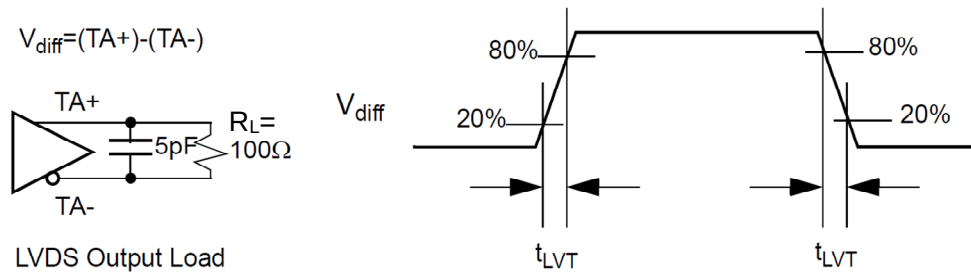


Figure 4. LVDS Output Load and Transition Time

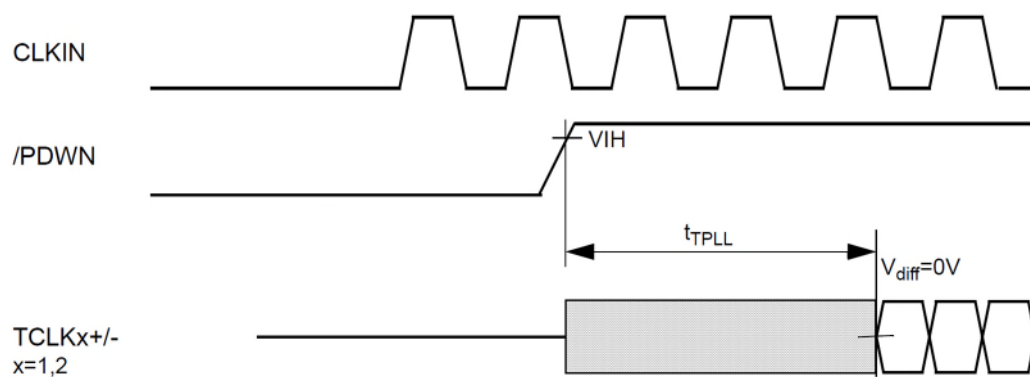
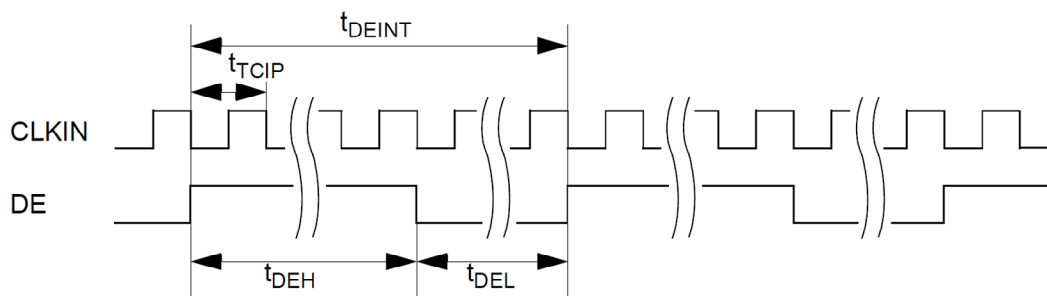


Figure 5. PLL Lock Time



Note: **Dual-out mode(MODE=L)**

The period between rising edges of DE (t_{DEINT}), high time of DE (t_{DEH}) should always satisfy following equations.

$$t_{DEH} = t_{TCIP} * (2m)$$

$$t_{DEINT} = t_{TCIP} * (2n)$$

$$m, n = \text{integer}$$

Figure 6. Dual-out mode DE input timing

AC Timing Diagrams(Continued)

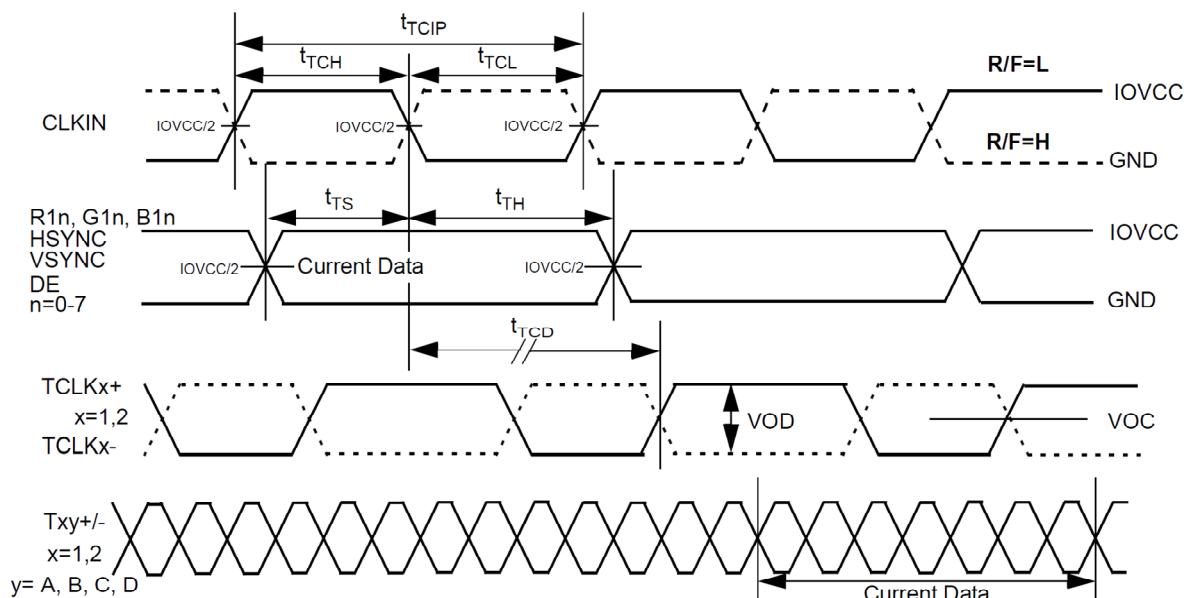


Figure 7. CLKIN Period, High/Low Time, Setup/Hold Timing for Single Edge Input Mode

MODE = H or DDRN = H

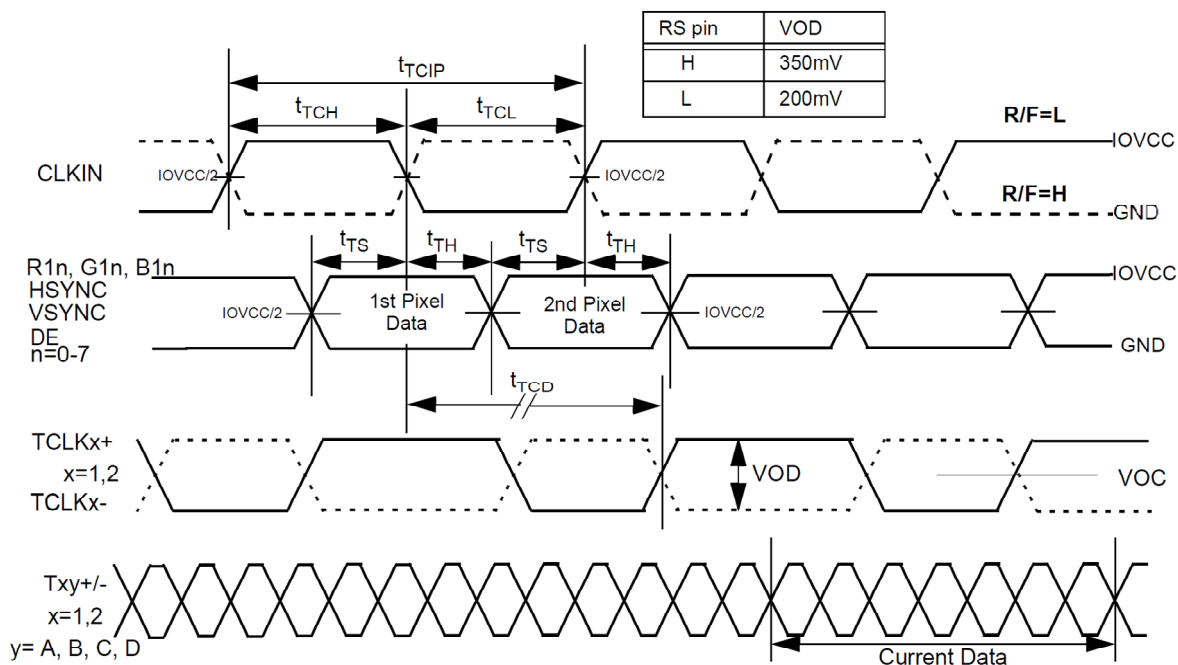


Figure 8. CLKIN Period, High/Low Time, Setup/Hold Timing for Double Edge Input Mode(DDR)

MODE = L, DDRN = L

AC Timing Diagrams(Continued)

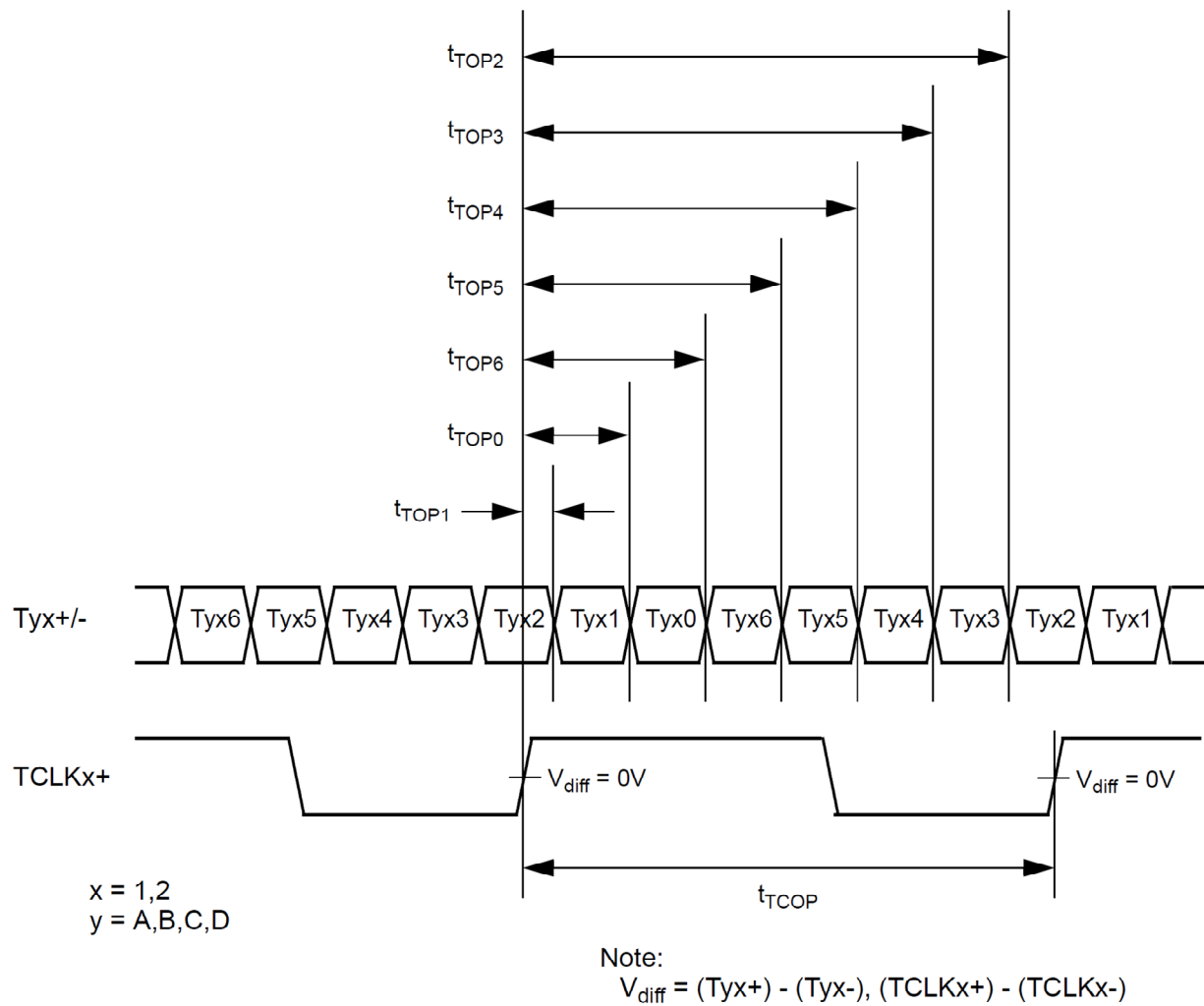


Figure 9. LVDS Output Data Position

Single-In / Dual-Out Mode (MODE = L)

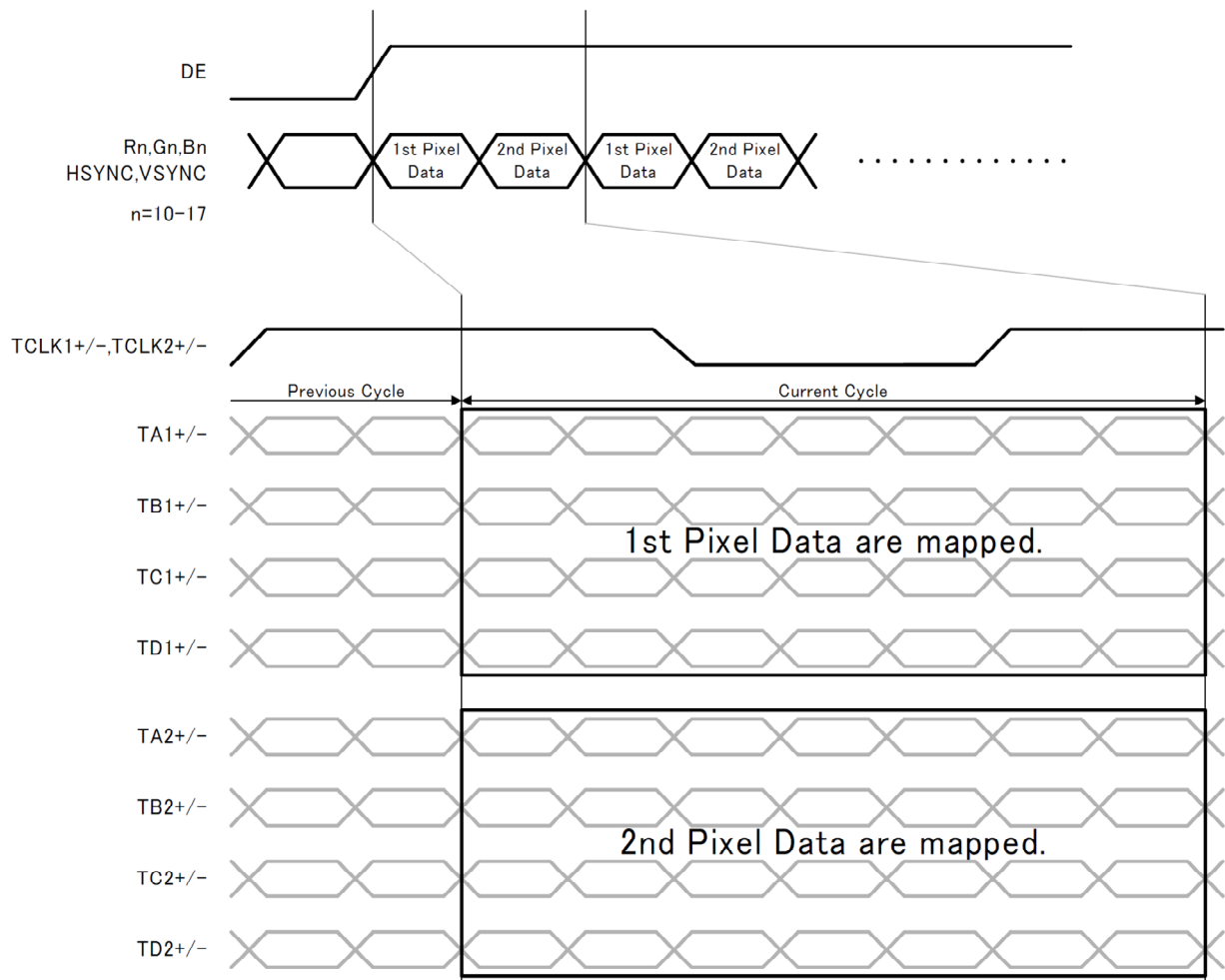


Figure 10. Single-In / Dual-Out Mode (MODE = L)

Single-In / Single-Out Mode (MODE = H)

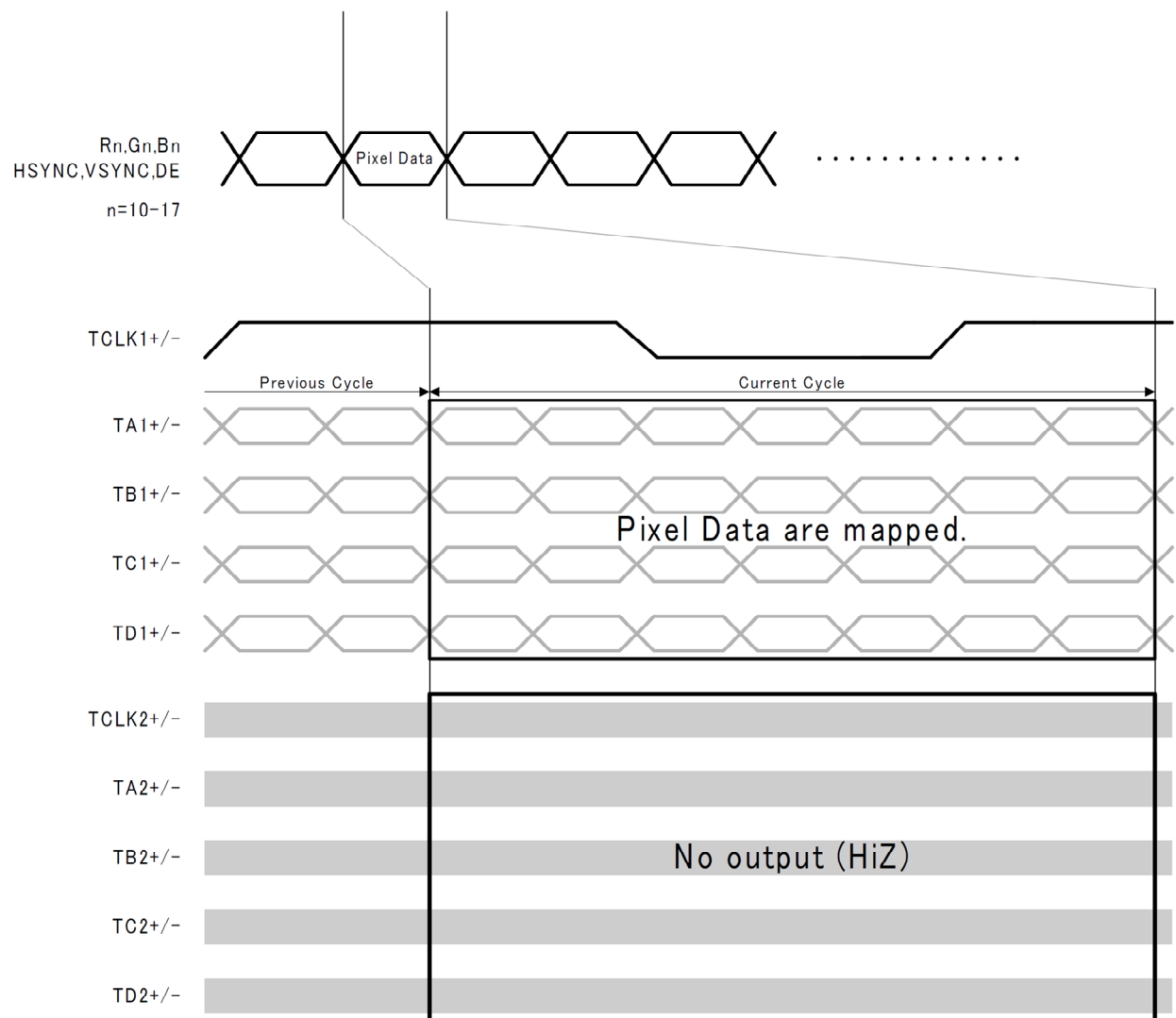
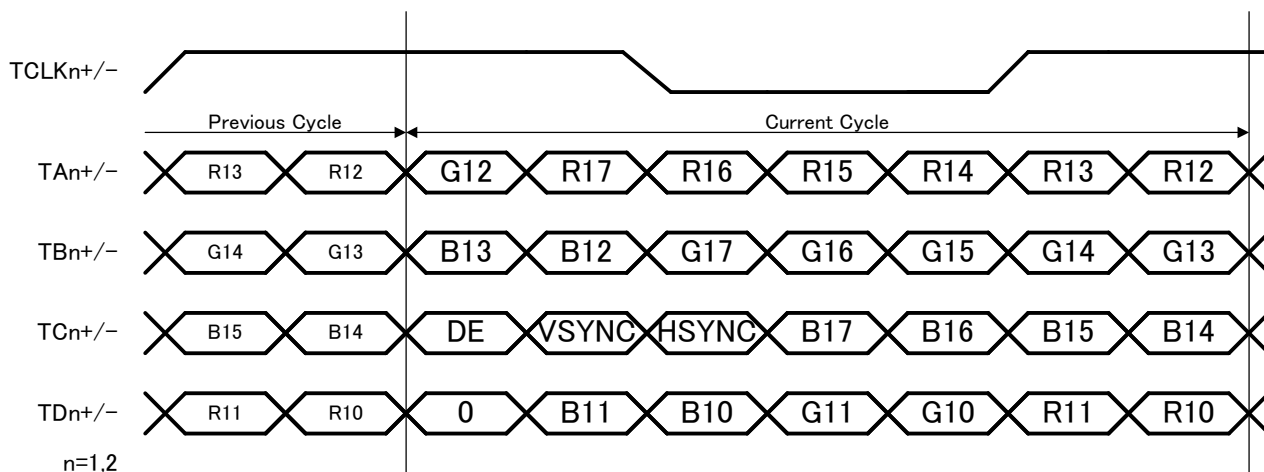
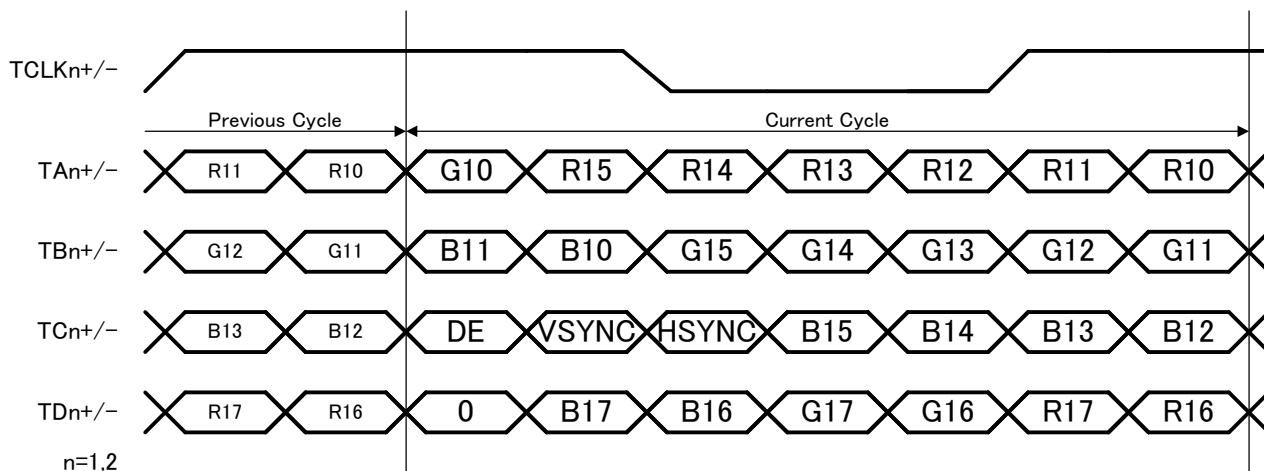


Figure 11. Single-In / Single-Out Mode (MODE = H)

LVDS Data Mapping for 8 bit Mode (6B/8B = L)



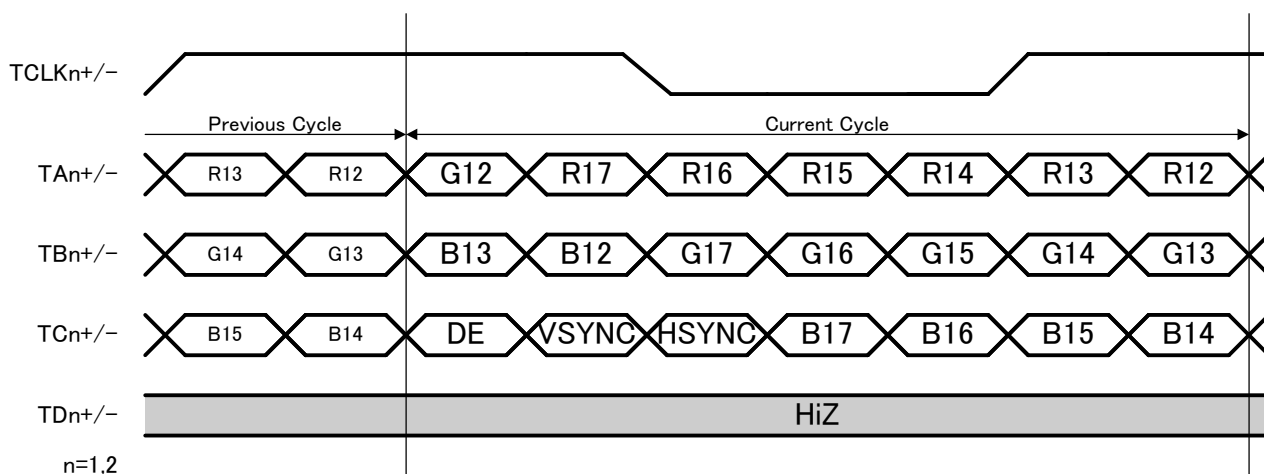
(a) LVDS Data Mapping when MAP = H (Mapping Mode 1)



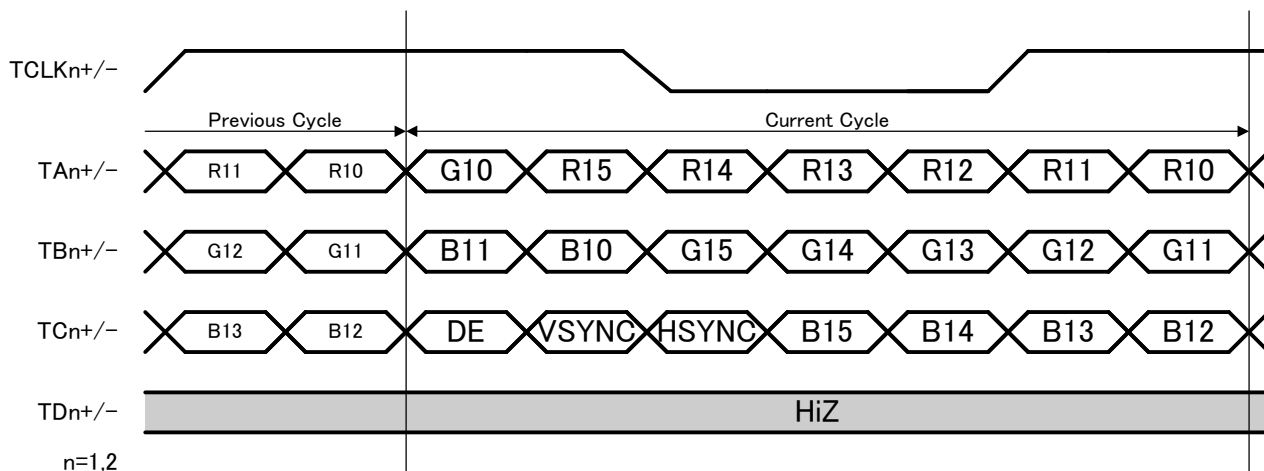
(b) LVDS Data Mapping when MAP = L (Mapping Mode 2)

Figure 12. LVDS Data Mapping for 8 bit Mode (6B/8B = L)

LVDS Data Mapping for 6 bit Mode (6B/8B = H)



(a) LVDS Data Mapping when MAP = H (Mapping Mode 1)



(b) LVDS Data Mapping when MAP = L (Mapping Mode 2)

Figure 13. LVDS Data Mapping for 6 bit Mode (6B/8B = H)

Note: Input pins which are not used in 6 bit Mode (R10-11, G10-11, B10-11 on Mapping Mode 1, R16-17, G16-17, B16-17 on Mapping Mode 2) can be H, L, or Open.

Note

1) Cable Connection and Disconnection

Don't connect and disconnect the LVDS cable, when the power is supplied to the system.

2) GND Connection

Connect the each GND of the PCB which THC63LVD827 and LVDS-Rx on it. It is better for EMI reduction to place GND cable as close to LVDS cable as possible.

3) Multi Drop Connection

Multi drop connection is not recommended.

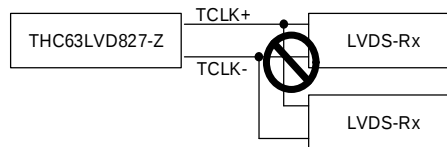


Figure 14. Multi Drop Connection

4) Asynchronous Use

Asynchronous use such as following systems are not recommended.

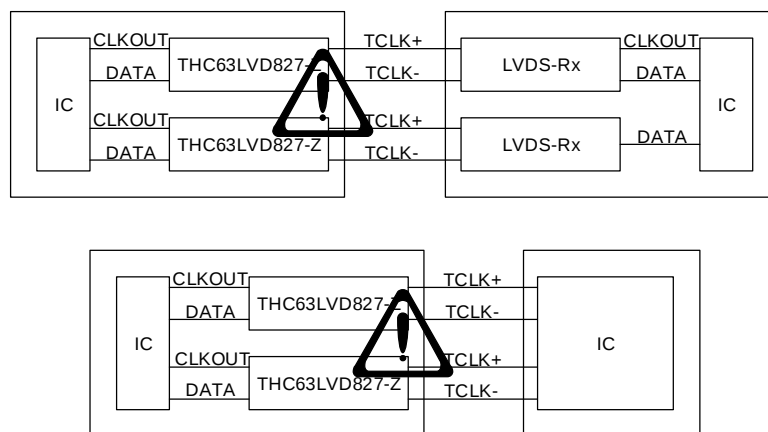
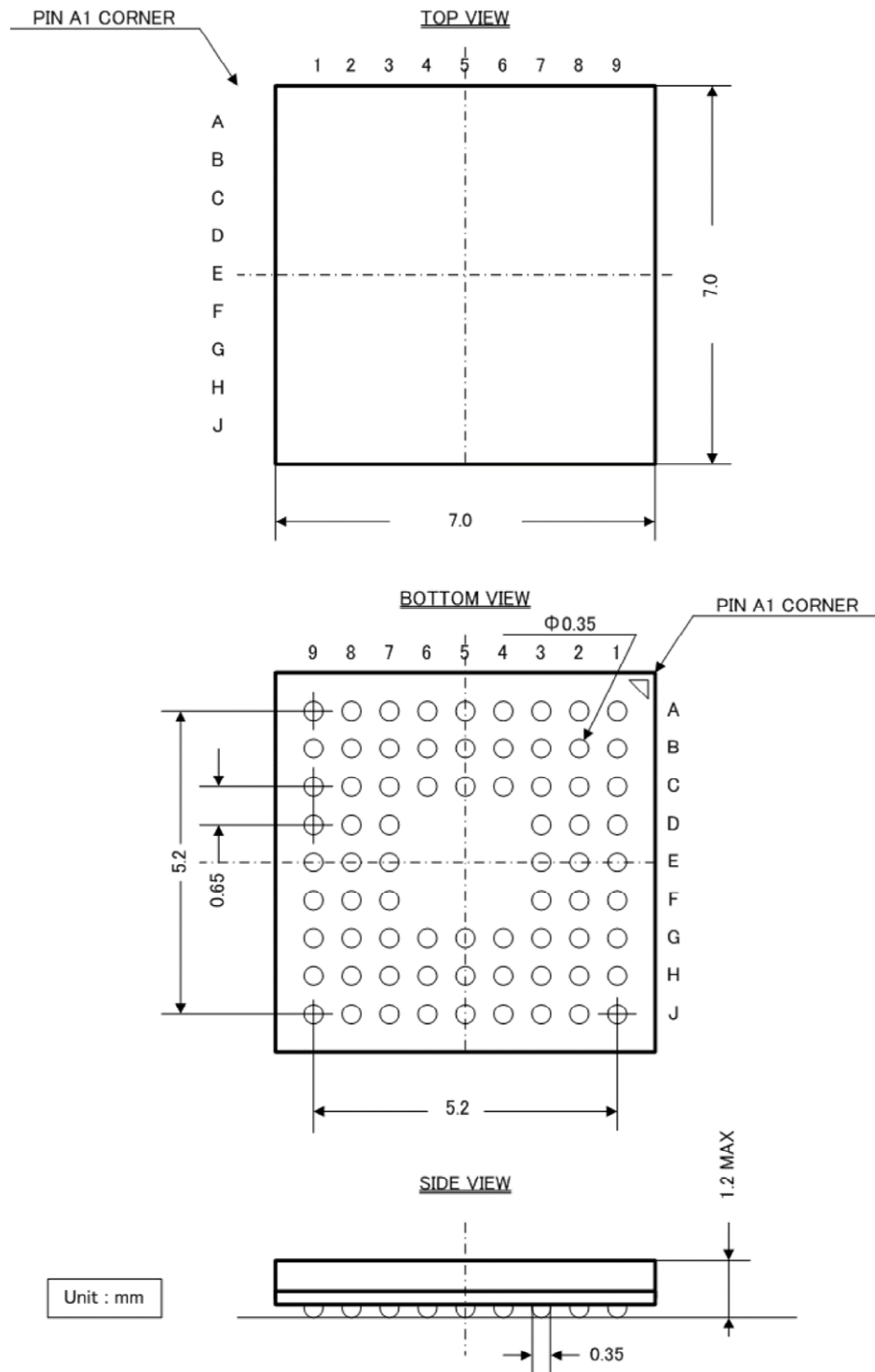


Figure 15. Asynchronous Use

Package

TFBGA

**Figure 16. Package Diagram**

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